



Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

A. Samsung Part Number

- Samsung P/N : CL21C681JBC1PNC
- Description : CAP, 680pF, 50V, ±5%, C0G, 0805
- AEC-Q 200 Specified

| | | <u>CL</u> ① | <mark>21</mark> ② | <u>C</u> 3 | <u>681</u> ④ | <mark>_</mark> 5 | <u>B</u> 6 | <mark>C</mark> ⑦ | <u>1</u> ® | <u>P</u> 9 | <u>N</u> 10 | <mark>C</mark> 10 | |
|------------|---------------|--|----------------------|---------------|-----------------|---------------------|---------------|---------------------|---------------|---------------|----------------|----------------------|---------------------|
| 1 | Series | Series Samsung Multi-layer Ceramic Capacitor | | | | | | | | | | | |
| 2 | Size | 0805 (inch c | ode) | | L: | 2.0 | ± 0.1 | mm | | | W: | 1.25 ± 0.1 | mm |
| 3 | Dielectric | C0G | | | | 8 | Inner | electr | ode | | | Ni | |
| 4 | Capacitance | 680 pF | | | | | Termi | natio | n | | | Cu | |
| 5 | Capacitance | ±5 % | | | | | Platin | g | | | | Sn 100% | (Pb Free) |
| | tolerance | | | | | 9 | Produ | ıct | | | | Automotive | |
| 6 | Rated Voltage | 50 V | | | | 10 | Grade | e code | • | | | Standard | |
| \bigcirc | Thickness | 0.85 ± 0.1 | mm | | | 1 | Packa | aging | | | | Cardboard Typ | e, 7" reel(4,000ea) |

B. Reliability Test and Judgement condition

| | Performance | Test condition | | | | | |
|----------------------|---|--|--|--|--|--|--|
| High Temperature | Appearance : No abnormal exterior appearance | Unpowered, 1000hrs@T=150°C | | | | | |
| Exposure | Capacitance Change : | Measurement at 24±2hrs after test conclusion | | | | | |
| | within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger | | | | | | |
| | Q : 1000 min | | | | | | |
| | IR : More than 10,000₩ or 500₩×μF | | | | | | |
| | Whichever is Smaller | | | | | | |
| Temperature Cycling | Appearance : No abnormal exterior appearance | 1000Cycles | | | | | |
| | Capacitance Change : | Measurement at 24±2hrs after test conclusion | | | | | |
| | within ±2.5% or ±0.25 ${\rm pF}$ whichever is larger | 1 cycle condition : | | | | | |
| | Q : 1000 min | -55+0/-3 ℃(15±3min) -> Room Temp(1min.) | | | | | |
| | IR : More than 10,000₩ or 500₩xµF | -> 125+3/-0℃(15±3min) -> Room Temp(1min.) | | | | | |
| | Whichever is Smaller | | | | | | |
| Destructive Physical | No Defects or abnormalities | Per EIA 469 | | | | | |
| Analysis | | | | | | | |
| Moisture Resistance | Appearance : No abnormal exterior appearance | 10Cycles, t=24hrs/cycle | | | | | |
| | Capacitance Change : | Heat (25~65 $^\circ \!\! C$) and humidity (80~98%), Unpowered | | | | | |
| | within ±2.5% or ±0.25 ${\rm pF}$ whichever is larger | measurement at 24±2hrs after test conclusion | | | | | |
| | Q : 350 min | | | | | | |
| | IR : More than 10,000№ or 500№×µF | | | | | | |
| | Whichever is Smaller | | | | | | |
| Humidity Bias | Appearance : No abnormal exterior appearance | 1000hrs 85℃/85%RH, Rated Voltate and 1.3~1.5V, | | | | | |
| | Capacitance Change : | Add 100kohm resistor | | | | | |
| | within ±2.5% or ±0.25 \ensuremath{pF} whichever is larger | Measurement at 24±2hrs after test conclusion | | | | | |
| | Q : 200 min | The charge/discharge current is less than 50mA. | | | | | |
| | IR : More than 500MQ or $25MQ \times \mu F$ | | | | | | |
| | Whichever is Smaller | | | | | | |
| High Temperature | Appearance : No abnormal exterior appearance | 1000hrs @ TA=125℃, 200% Rated Voltage, | | | | | |
| Operating Life | Capacitance Change : | Measurement at 24±2hrs after test conclusion | | | | | |
| | within $\pm 3.0\%$ or $\pm 0.3 \text{ pF}$ whichever is larger | The charge/discharge current is less than 50mA. | | | | | |
| | Q : 350 min | | | | | | |
| | IR : More than 10,000M Ω or 500M $\Omega 	imes \mu$ F | | | | | | |
| | Whichever is Smaller | | | | | | |

| | Performance | Test condition | | | | | | |
|---------------------|--|--|--|--|--|--|--|--|
| External Visual | No abnormal exterior appearance | Visual inspection | | | | | | |
| | | | | | | | | |
| Physical Dimensions | Within the specified dimensions | Using The calipers | | | | | | |
| | | | | | | | | |
| Mechanical Shock | Appearance : No abnormal exterior appearance | Three shocks in each direction should be applied along | | | | | | |
| | Capacitance Change : | 3 mutually perpendicular axes of the test specimen (18 shocks) | | | | | | |
| | within ±2.5% or ±0.25 ${}_{\text{P}}\text{F}$ whichever is larger | Peakvalue Duration Wave Velocity | | | | | | |
| | Q, IR : initial spec. | 1,500G 0.5ms Half sine 4.7m/sec. | | | | | | |
| Vibration | Appearance : No abnormal exterior appearance | 5g's for 20min., 12cycles each of 3 orientations, | | | | | | |
| | Capacitance Change : | Use 8"x5" PCB 0.031" Thick 7 secure points on one long side | | | | | | |
| | within ±2.5% or ±0.25pF whichever is larger | and 2 secure points at corners of opposite sides. Parts mounted | | | | | | |
| | Q, IR : initial spec. | within 2" from any secure point. Test from 10~2000Hz. | | | | | | |
| Resistance to | Appearance : No abnormal exterior appearance | Solder pot : 260±5°C, 10±1sec. | | | | | | |
| Solder Heat | Capacitance Change : | , , | | | | | | |
| | within ±2.5% or ±0.25pF whichever is larger | | | | | | | |
| | Q, IR : initial spec. | | | | | | | |
| Thermal Shock | Appearance : No abnormal exterior appearance | -55℃/+125℃. | | | | | | |
| | Capacitance Change : | Note: Number of cycles required-300, | | | | | | |
| | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | Maximum transfer time-20 sec, Dwell time-15min. Air-Air | | | | | | |
| | Q, IR : initial spec. | | | | | | | |
| ESD | Appearance : No abnormal exterior appearance | AEC-Q200-002 | | | | | | |
| | Capacitance Change : | | | | | | | |
| | within ±2.5% or ±0.25 ${}_{\text{p}}{}^{\text{F}}$ whichever is larger | | | | | | | |
| | Q, IR : initial spec. | | | | | | | |
| Solderability | 95% of the terminations is to be soldered | a) Preheat at 155 $^\circ\!\!\!\!\mathrm{C}$ for 4 hours, Immerse in solder for 5s at 245±5 $^\circ\!\!\!\mathrm{C}$ | | | | | | |
| | evenly and continuously | b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 $^\circ\!\mathrm{C}$ | | | | | | |
| | | c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 $^\circ \!\!\!\!^{\rm C}$ | | | | | | |
| | | solder : a solution ethanol and rosin | | | | | | |
| Electrical | Capacitance : Within specified tolerance | The Capacitance /Q should be measured at 25 $^\circ \!\!\! ^\circ \!\!\! ^\circ$, | | | | | | |
| Characterization | Q : 1000 max. | 1_±10%, 0.5~5Vrms | | | | | | |
| | IR(25℃) : More than 100,000№ or 1,000№×μF | I.R. should be measured with a DC voltage not exceeding | | | | | | |
| | IR(125℃) : More than10,000№ or 100№×μF | Rated Voltage @25°C, @125°C for 60~120 sec. | | | | | | |
| | Whichever is Smaller | Dielectric Strength : 250% of the rated voltage for 1~5 seconds | | | | | | |
| | Dielectric Strength | | | | | | | |
| Board Flex | Appearance : No abnormal exterior appearance | Bending to the limit (3mm) for 5 seconds | | | | | | |
| | Capacitance Change : | | | | | | | |
| Terminal | within ±5.0% or ±0.5pF whichever is larger Appearance : No abnormal exterior appearance | 18N for 60+1 coc | | | | | | |
| Strength(SMD) | Capacitance Change : | 18N, for 60±1 sec. | | | | | | |
| | within $\pm 2.5\%$ or $\pm 0.25pF$ whichever is larger | | | | | | | |
| Beam Load | Destruction value should not be exceed | Beam speed | | | | | | |
| | Chip Length < 2.5mm | 0.5±0.05mm/sec | | | | | | |
| | a) Chip Thickness > 0.5mm : 20N | | | | | | | |
| | b) Chip Thickness ≤ 0.5 mm : 20N | | | | | | | |
| Temperature | | | | | | | | |
| characteristics | (From -55°C to 125°C, Capacitance change should | be within +30PPM/°ር) | | | | | | |
| | 1. Tom 00 0 to 120 0, Oapaonance change should | | | | | | | |

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max) Meet IPC/JEDEC J-STD-020 D Standard

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.